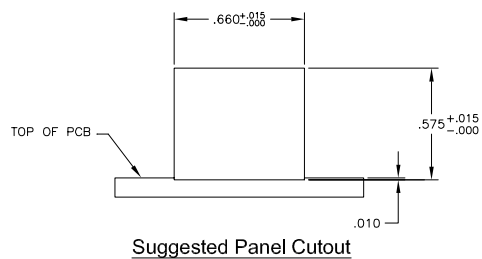
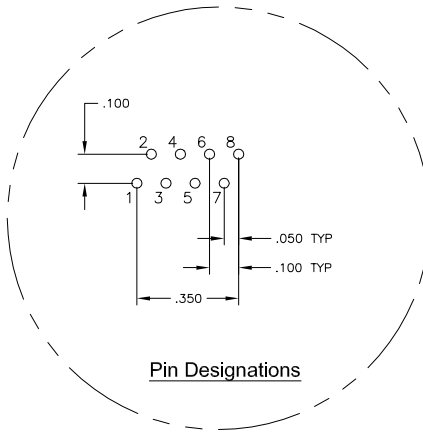
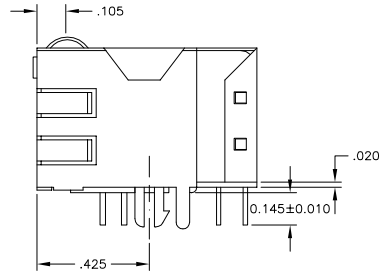
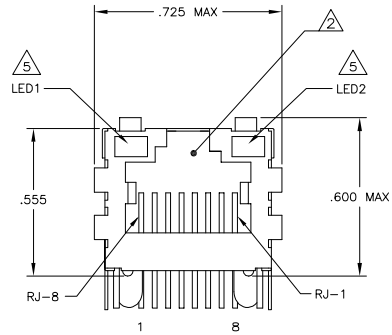
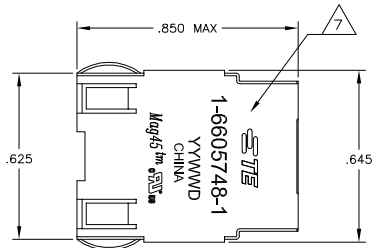
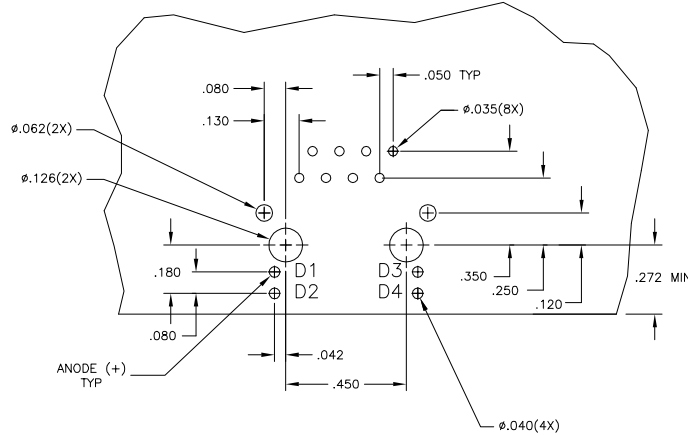
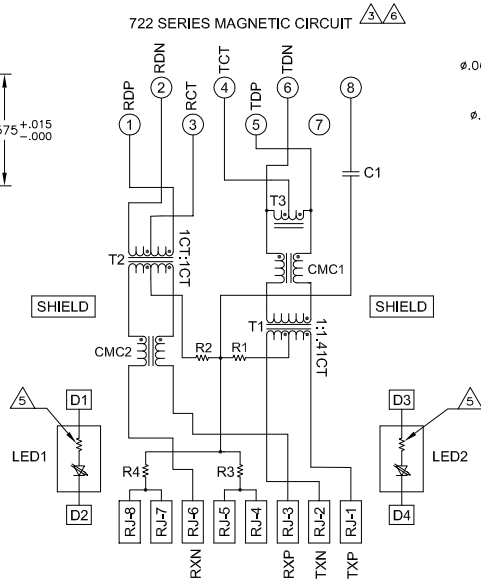


LOC	DATE	REVISIONS	DATE	BY	CHK
AA	22				
E2		REVISED PER ECO-11-005140	25MAR11	RK	HMR
F		ECO-11-015766	30MAY2011	EL	LR

**MECHANICAL:**



**722 SERIES MAGNETIC CIRCUIT**



**Suggested PCB Layout (Component Side)**

- MATERIALS:**  
 HOUSING - THERMOPLASTIC PET POLYESTER FLAMMABILITY RATING UL 94V-0.  
 SHIELD - .010" THICK, C26800 BRASS PREPLATED WITH 30μINCH MIN SEMI-BRIGHT NICKEL. SOLDER TABS POST DIPPED WITH 100μINCH MIN SAC SOLDER.  
 MOD JACK CONTACTS - 0.0157 X 0.018" PHOSPHOR BRONZE, 50μINCH MIN OVERALL NICKEL UNDERPLATE WITH SELECT 50μINCH MIN HARD GOLD FINISH PLATE.  
 SOLDER TAILS WITH 100μINCH MIN MATTE TIN AND/OR SAC SOLDER DIP.  
 LIGHT EMITTING DIODE(LED) - DIFFUSED EPOXY LENS, .020" X .020" CARBON STEEL WIREFRAME LEADS PRE-PLATED WITH 80μINCH SILVER OVER 40μINCH NICKEL UNDERPLATE OVER 40μINCH COPPER UNDERPLATE. POST-PLATED WITH 100μINCH MIN MATTE TIN AND/OR SAC SOLDER DIP OR PURE TIN SOLDER DIP.
- RJ45 JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUB PART F.**
- MAGNETICS**  
 -APPLICATION: 10/100 BASE-T  
 -IMPEDANCE: 100 OHMS  
 -TURNS RATIO (CHIP:CABLE): TX = 1:141, RX = 1:1  
 -OPEN CIRCUIT INDUCTANCE (OCL): 350μH MIN @100kHz, 0.1VRMS, 8mADC BIAS FROM 0°C TO 70°C, TX AND RX  
 -PERFORMANCE @ 25°C:  
 INSERTION LOSS (IL): 1.1dB MAX FROM 0.5MHz TO 100MHz  
 RETURN LOSS (RL): 18dB MIN FROM 0.5MHz TO 30MHz  
 18-20LOG(f/30)dB MIN FROM 30.1MHz TO 60MHz  
 12dB MIN FROM 60.1MHz TO 80MHz  
 CROSSTALK ATTENUATION: 35dB MIN FROM 0.5MHz TO 40MHz  
 33-20LOG(f/50)dB MIN FROM 4.0.1MHz TO 100MHz  
 COMMON MODE REJECTION RATIO (CMRR): 30dB MIN FROM 0.5MHz TO 100MHz  
 -ISOLATION VOLTAGE: 2250VDC (MAX) FOR 60 SECONDS WITH A RISE TIME OF 500V/SEC.
- 4 OPERATING TEMPERATURE: FROM 0°C TO +70°C.**
- THE 250 OHM RESISTOR IS OPTIONAL, PLEASE SEE CHART FOR PRESENCE OR ABSENCE OF LED RESISTORS.**  
 IF LEADS WITHOUT 250 OHM RESISTOR, LEADS ARE DRIVEN WITH CONSTANT CURRENT AT APPROX 20 mA  
 LED COLOR: DOMINANT WAVELENGTH (AD): GREEN 568 nm TYP @ IF=20 mA  
 FORWARD VOLTAGE (VF): GREEN 2.2V TYP @ IF=20 mA  
 DOMINANT WAVELENGTH (AD): YELLOW 588 nm TYP @ IF=20 mA  
 FORWARD VOLTAGE (VF): YELLOW 2.1V TYP @ IF=20 Ma  
 IF LEADS WITH BUILT-IN RESISTOR, LEADS ARE DRIVEN WITH 5V VOLTAGE AND THE MAX OPERATING CURRENT IS 20mA.  
 LED COLOR: DOMINANT WAVELENGTH (AD): GREEN 568 nm TYP @ VF=5V  
 FORWARD CURRENT (IF): GREEN 12mA TYP @ VF=5V  
 DOMINANT WAVELENGTH (AD): YELLOW 588 nm TYP @ VF=5V  
 FORWARD CURRENT (IF): YELLOW 13mA TYP @ VF=5V
- INDICATED CONNECTIONS ARE FOR NIC CONFIGURATION. THE MAGNETICS ARE ASYMMETRIC, AND DO NOT SUPPORT AUTO-MDI/MDIX.**
- TE CONNECTIVITY LOGO, TE CONNECTIVITY PART NUMBER, DATE CODE, COUNTRY OF ORIGIN AND AGENCY APPROVAL MARKING IN APPROXIMATE LOCATION SHOWN.**
- 8. THESE PARTS ARE RECOMMENDED FOR WAVE SOLDERING PROCESS, PREHEAT TEMPERATURE IS 120°C TO 160°C, 120 SECONDS TO 180 SECONDS, PEAK WAVE SOLDERING TEMPERATURE IS 260°C MAX, 10 SECONDS MAX.**
- OBsolete PARTS: OBSOLETE CIS STREAMLINING PER D.RENAUD/D.SINISI**

C1 = 1000 pF, 2KV CAPACITOR  
 R1-R4 = 75 OHMS, 1/16 W, RESISTORS

REV	DESCRIPTION	DATE	BY	CHK
1	ISSUED FOR PRODUCTION	03/05/11	EL	LR
2	REVISED PER ECO-11-005140	25MAR11	RK	HMR
3	ECO-11-015766	30MAY2011	EL	LR

REV	DESCRIPTION	DATE	BY	CHK
1	ISSUED FOR PRODUCTION	03/05/11	EL	LR
2	REVISED PER ECO-11-005140	25MAR11	RK	HMR
3	ECO-11-015766	30MAY2011	EL	LR

REV	DESCRIPTION	DATE	BY	CHK
1	ISSUED FOR PRODUCTION	03/05/11	EL	LR
2	REVISED PER ECO-11-005140	25MAR11	RK	HMR
3	ECO-11-015766	30MAY2011	EL	LR

REV	DESCRIPTION	DATE	BY	CHK
1	ISSUED FOR PRODUCTION	03/05/11	EL	LR
2	REVISED PER ECO-11-005140	25MAR11	RK	HMR
3	ECO-11-015766	30MAY2011	EL	LR

REV	DESCRIPTION	DATE	BY	CHK
1	ISSUED FOR PRODUCTION	03/05/11	EL	LR
2	REVISED PER ECO-11-005140	25MAR11	RK	HMR
3	ECO-11-015766	30MAY2011	EL	LR

REV	DESCRIPTION	DATE	BY	CHK
1	ISSUED FOR PRODUCTION	03/05/11	EL	LR
2	REVISED PER ECO-11-005140	25MAR11	RK	HMR
3	ECO-11-015766	30MAY2011	EL	LR